



XIth Meeting of the Spanish Network for Future Linear Colliders

R&D on u-strip sensors @ SDR

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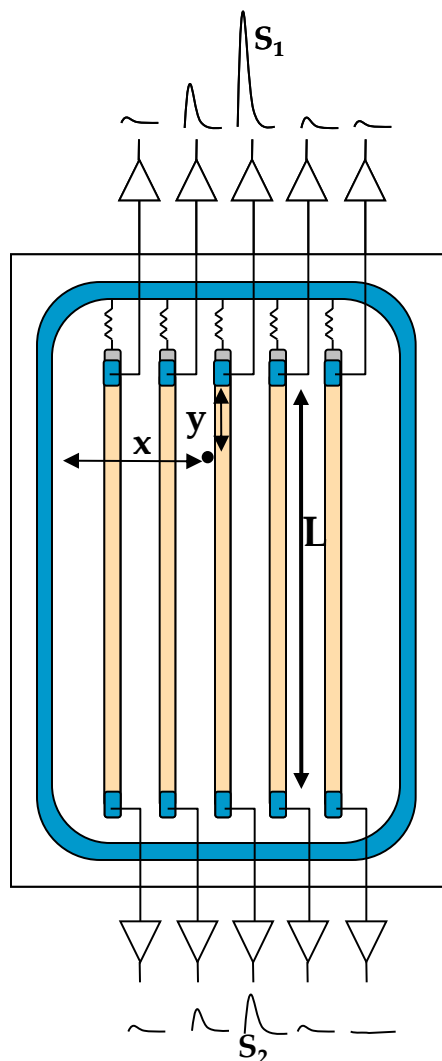


Outline

- Motivations for the R&D.
- A 2D position sensitive microstrip sensor.
 - Laser, radioactive source and particle beam characterization
- Improving the design
 - Integrated signal routing lines (Crosstalk suppression).
 - Incrementing the signal: Low Gain Avalanche Detectors.
- Summary

- Charge division in microstrips:
 - Long microstrips ladders (several tens of centimeters) proposed for the ILC tracking detectors.
 - Getting the particle hit coordinate along the strip using the charge division method.
 - Avoid the complexity of double sided sensors and the additional material of a second layer of sensors.
- Low gain segmented p-type pixels (strips)
 - Implementing a small gain in the segmented diode so we can reduce the thickness of the sensors without reducing the signal amplitude
 - Smaller contribution to the material budget.

Charge Division in uStrips



Simple single-side AC-coupled microstrip detectors
with resistive coupling electrodes.

X-coordinate: cluster-finding algorithms for strip detectors.

Y-coordinate: Resistive charge division method.

Resistive material
Aluminium

** Electrode resistance \gg preamplifier impedance.

$$S_1 = f(y)$$

$$S_2 = f(L - y)$$

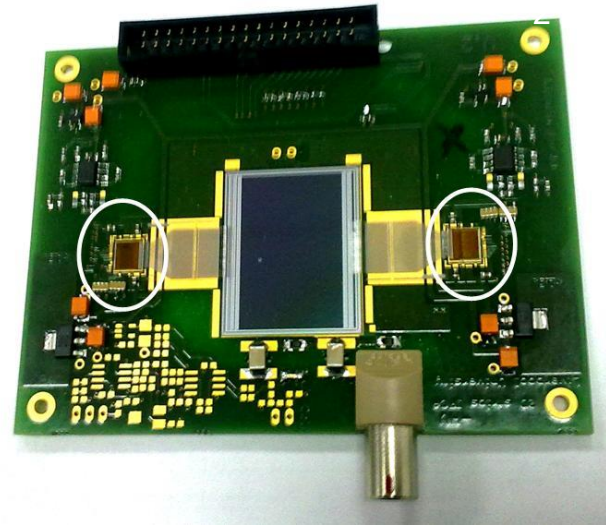
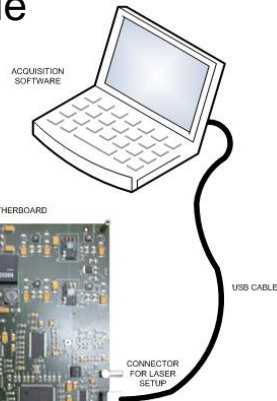
$$\frac{y}{L} = \frac{A_2}{A_1 + A_2}$$

Resistive material: high doped polysilicon

** V. Radeka, IEEE Transaction on Nuclear Science NS-21 (1974) 51

Proof-of-Concept Prototype

ALIBAVA DAQ system for microstrip detectors, based on the **Beetle** analogue readout ASIC



Strip:
length = 20 mm
width = 20 μm
Pitches:
Implant = 80 μm
readout = 80 μm
Electrode:
 $R/\mu\text{m} = 2.8 \text{ Ohms}/\mu\text{m}$
 $R/\mu\text{m} = 12.2 \text{ Ohms}/\mu\text{m}$

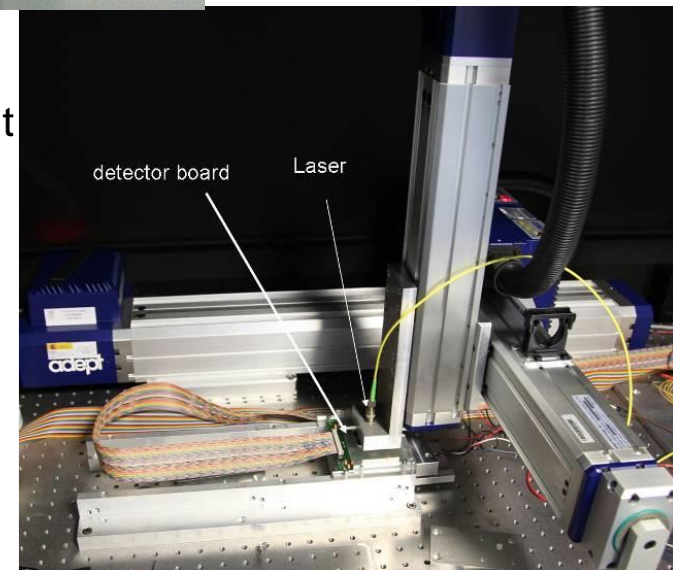
3D axis stage with displacement accuracy $\approx 10 \mu\text{m}$

Pulsed DFB laser
 $\lambda = 1060 \text{ nm}$

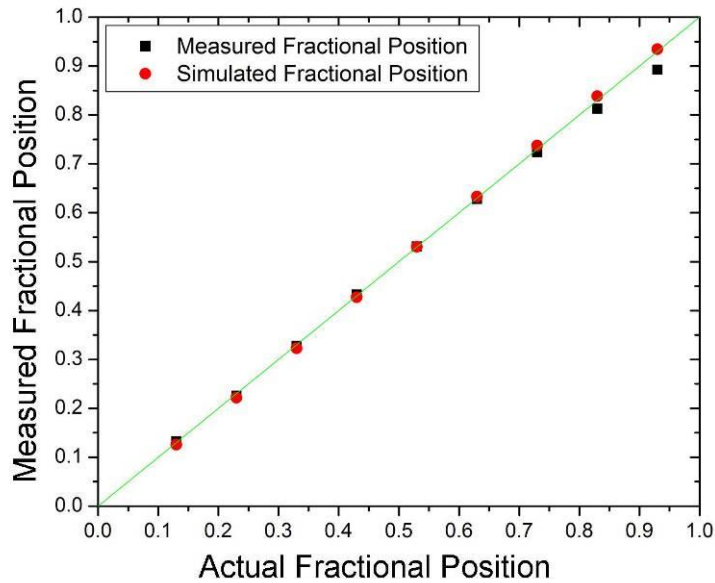
- 256 channels
- peaking time = 25 ns
- $S/N \approx 20$ for standard no irradiated detectors

- Gaussian beam spot width $\approx 15 \mu\text{m}$
- pulse duration 2 ns

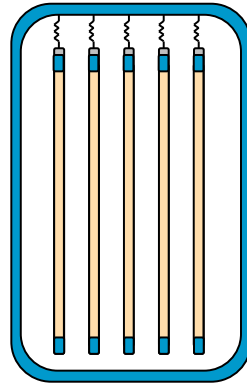
Clean room laboratory at IFCA, Santander



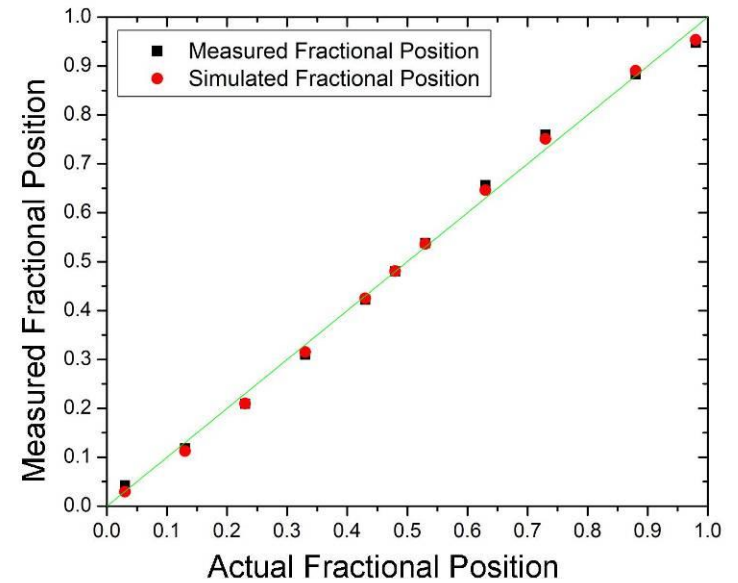
$R/l=2.8 \text{ } \Omega/\mu\text{m}$



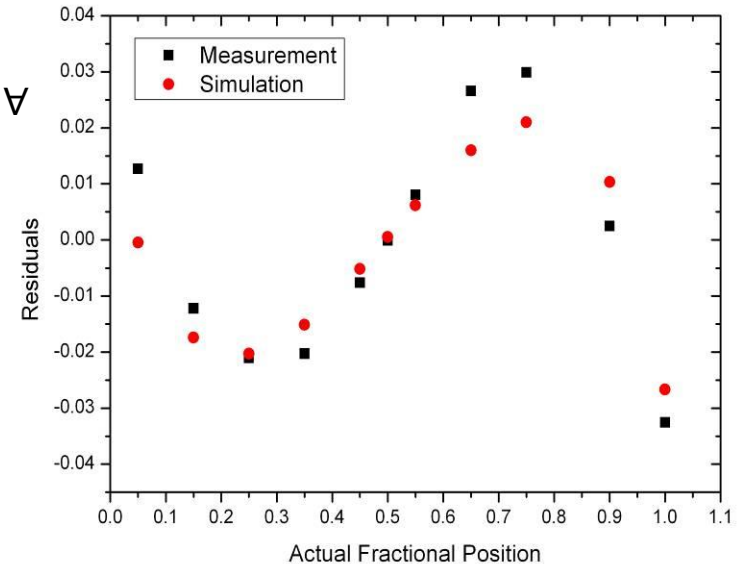
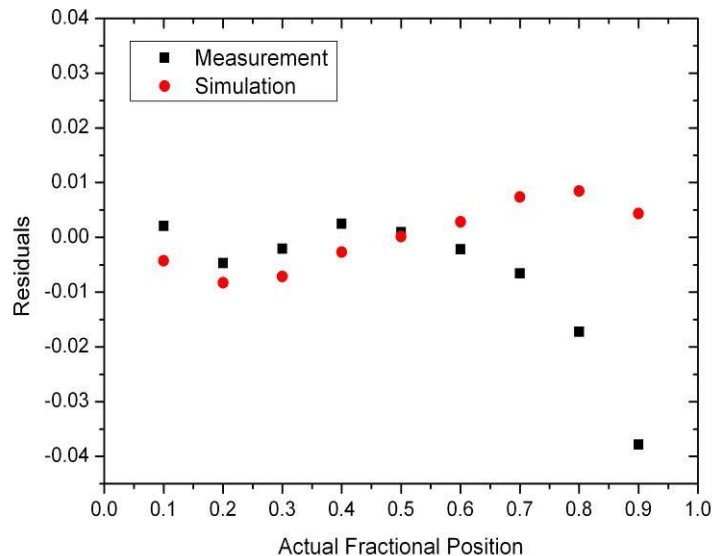
$$\frac{y}{L} = \frac{A_2}{A_1 + A_2}$$



$R/l=12.2 \text{ } \Omega/\mu\text{m}$



20000 events \forall measurement



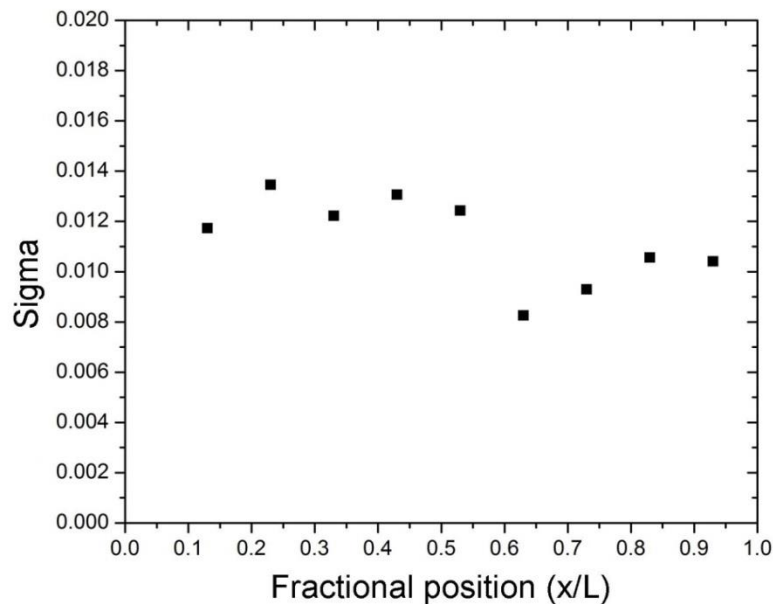
Longitudinal spatial resolution for 6 MIPs signal

$$\frac{A_2}{A_1 + A_2}$$

$$\sigma = \frac{A_1 A_2}{(A_1 + A_2)^2} \sqrt{\left(\frac{\sigma_{A_1}}{A_1}\right)^2 + \left(\frac{\sigma_{A_2}}{A_2}\right)^2 - 2\rho \left(\frac{\sigma_{A_1}}{A_1} \frac{\sigma_{A_2}}{A_2}\right)},$$

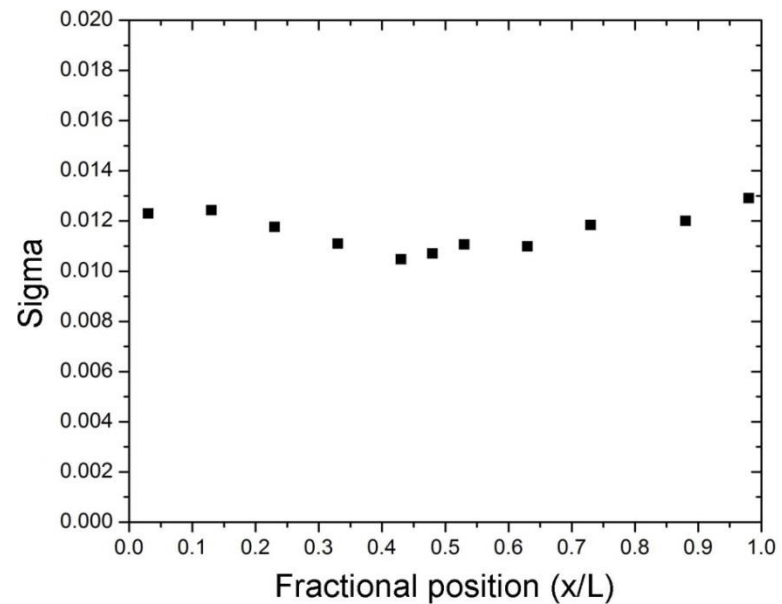
1.1% L => 220 μm

R/l=2.8 $\Omega/\mu\text{m}$



1.2% L => 240 μm

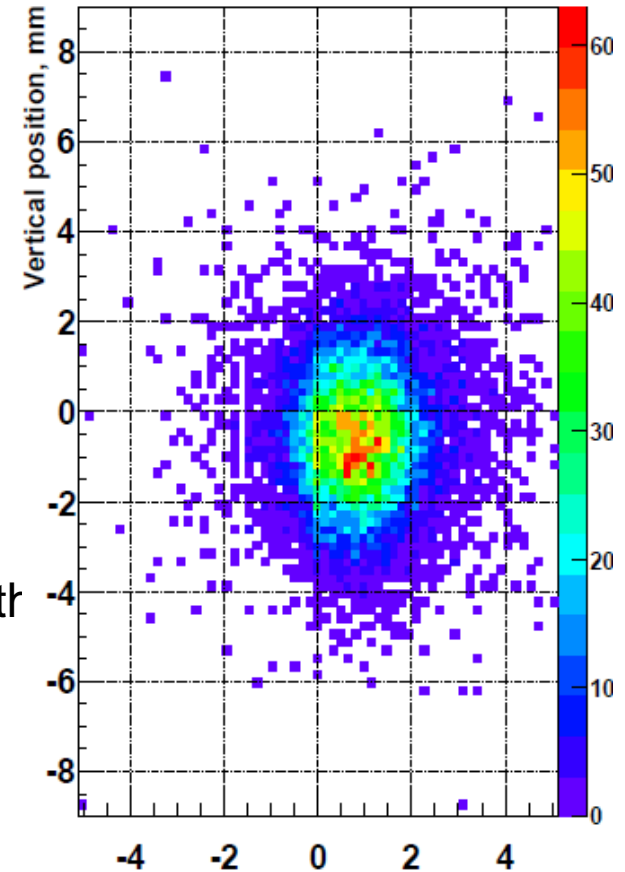
R/l=12.2 $\Omega/\mu\text{m}$



Test Beam Characterization



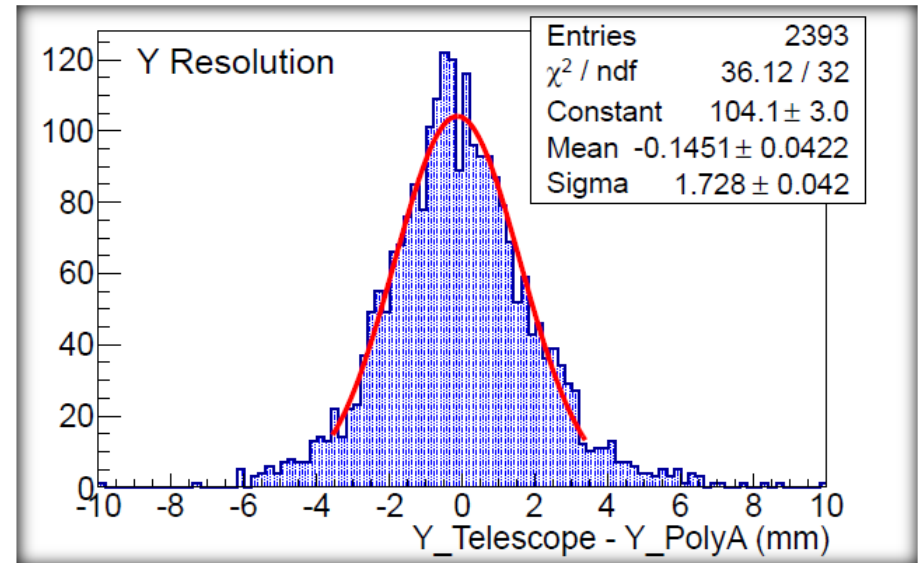
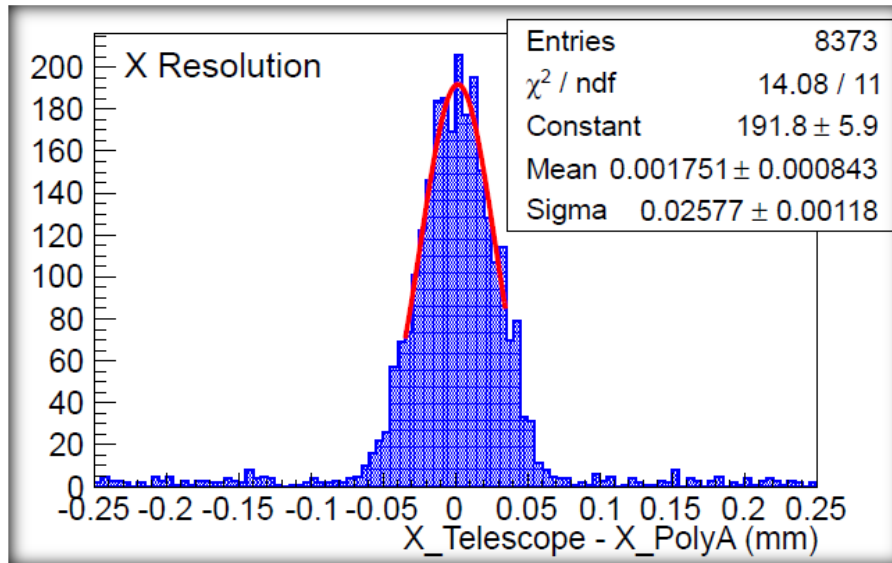
- Test beam at CERN SPS Pion Beam, Nov 2012
- First successful integration and synchronization with AIDA MIMOSA pixel telescope



Test Beam: Spatial Resolution

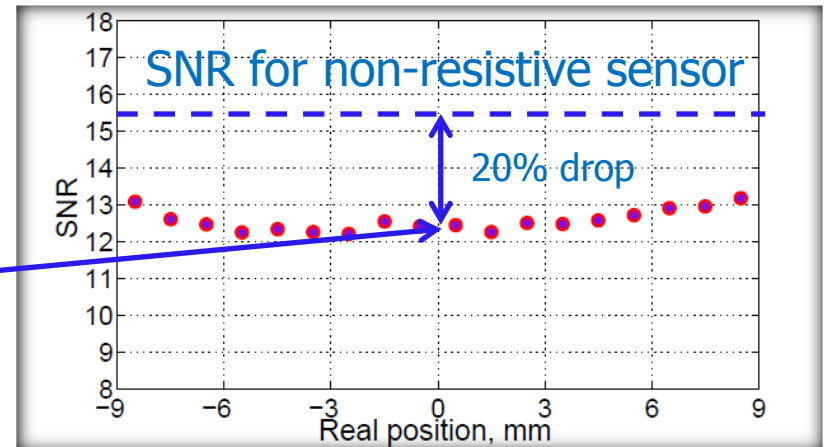
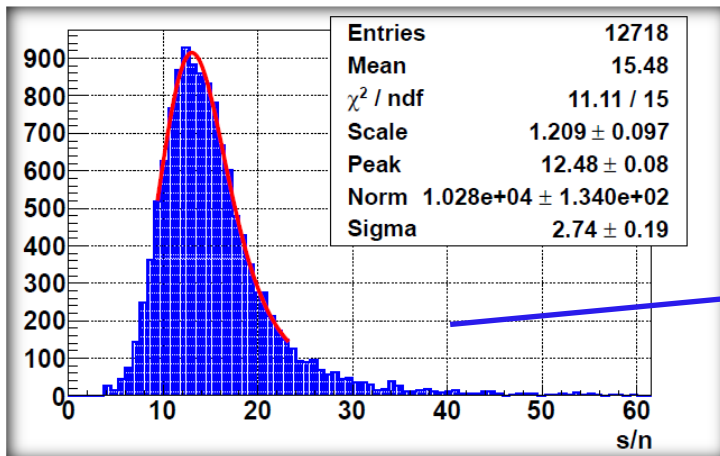
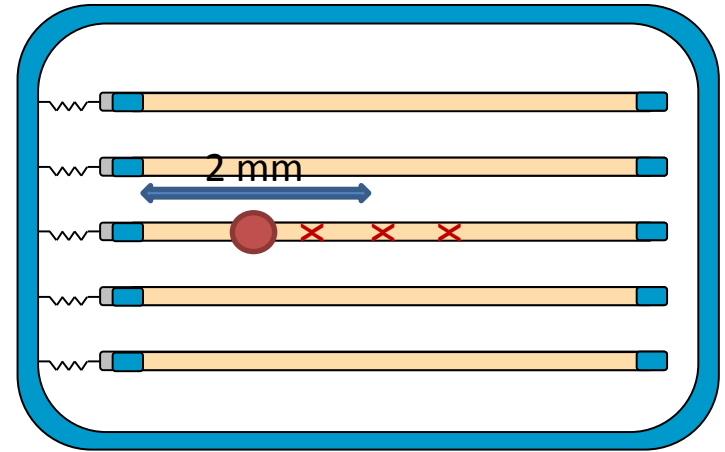
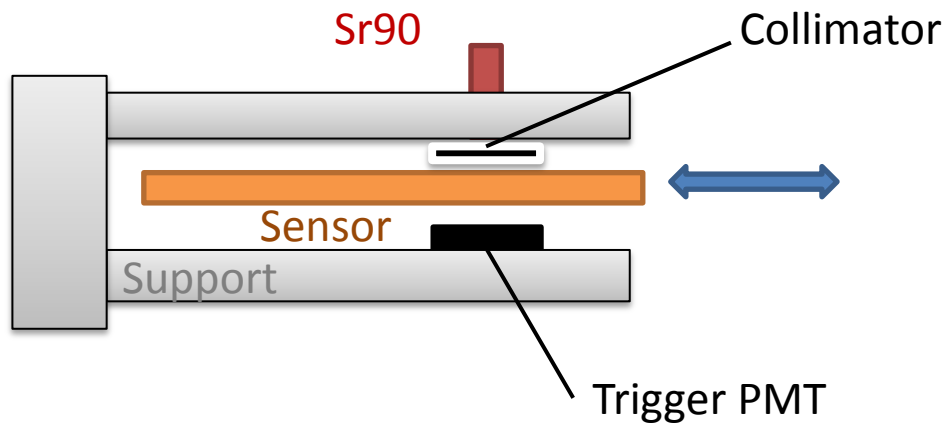
Trans. Coordinate X $\sim 25 \mu\text{m}$ (pitch/ $\sqrt{12}=23 \mu\text{m}$)

Long. Coordinate Y $\sim 1.7 \text{ mm}$ (8.5% strip length)



Radioactive Source: SNR estimation

Defined as $SNR \equiv (S1 + S2) / \sqrt{\sigma1 + \sigma2}$ (drives the spatial resolution)

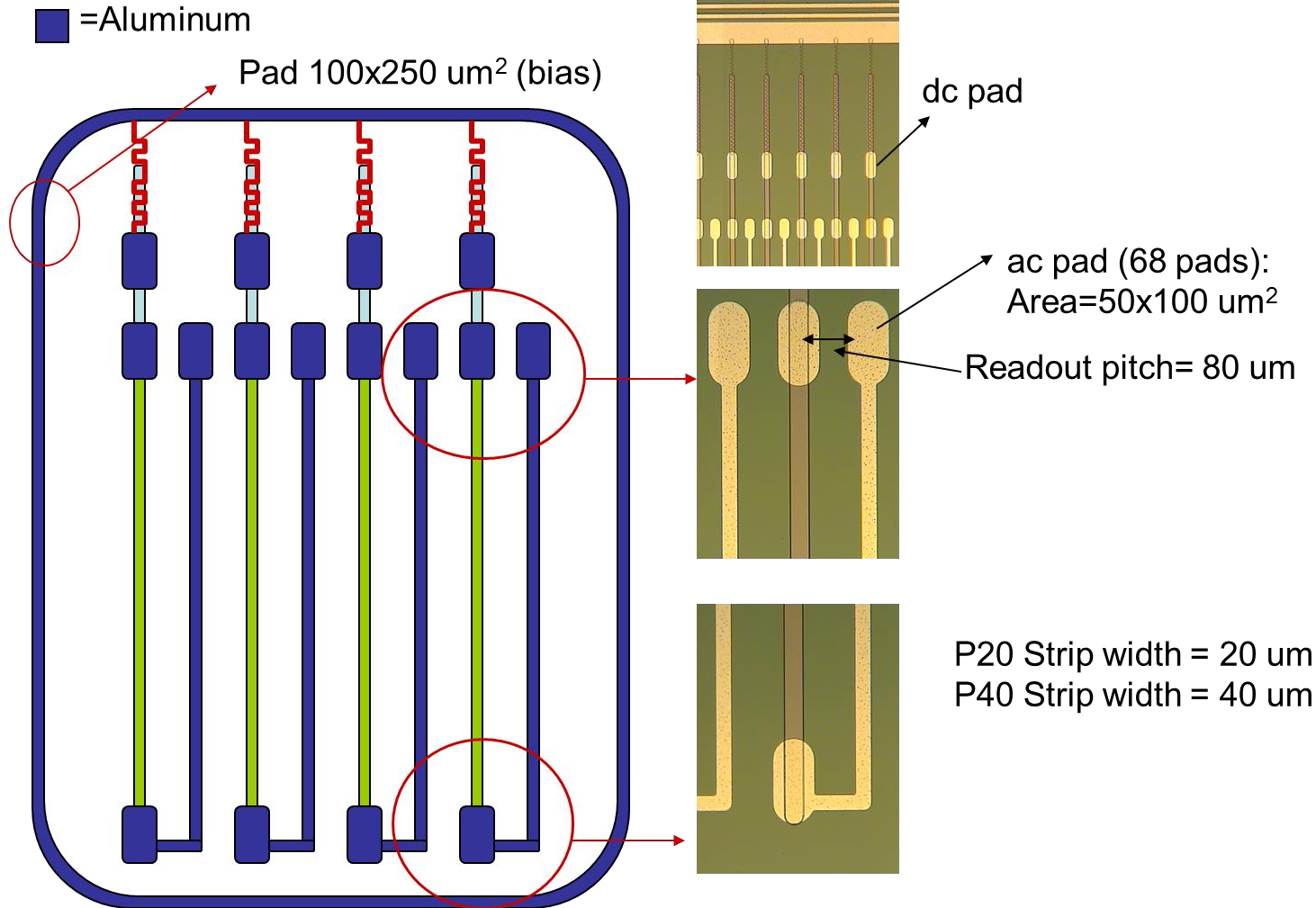


Charge-division sensor: Intermediate summary



- The charge-division concept on microstrips has been confirmed experimentally, two limitations:
 - Both ends readout difficult to integrate in long ladder (need to combine the information from both ends)
 - Signal attenuation due to the strip resistance (current prototypes 20% signal loss for 2cm length sensor).
- Proposed solutions:
 - Integrated signal lines in the sensor to route the signals to the same end.
 - Reduce the strip resistivity (limited by the amp. charge resolution) and/or integrate charge amplification mechanism in the sensor.

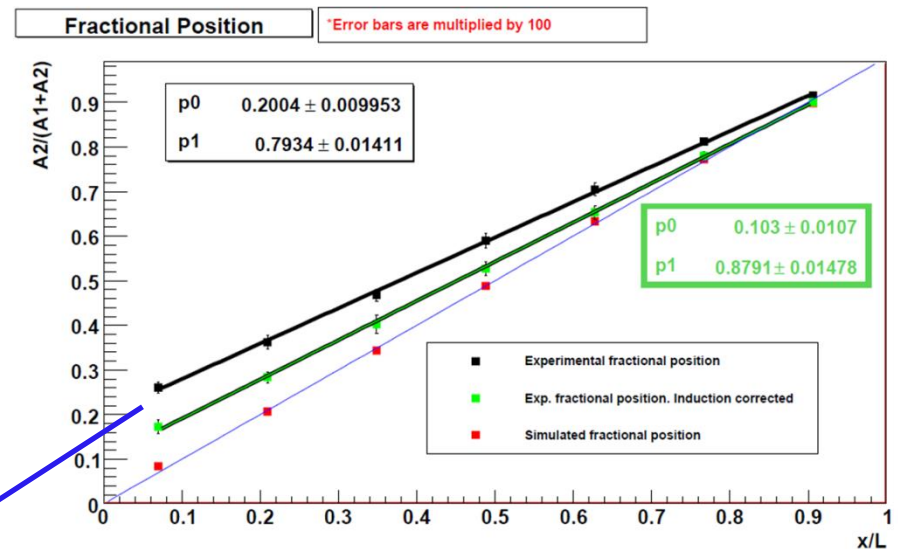
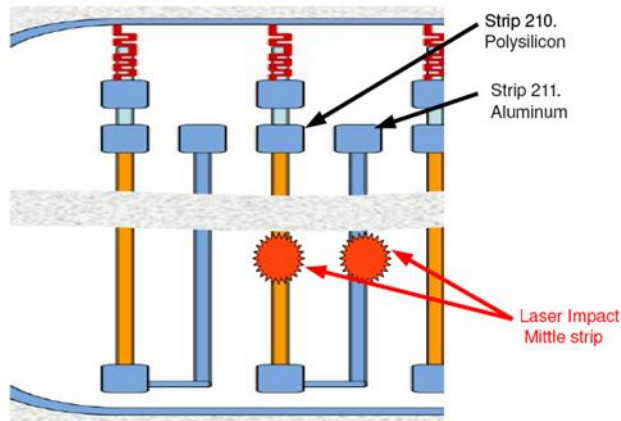
Resistive strips with internal signal routing



Resistive strips with internal signal routing (2)

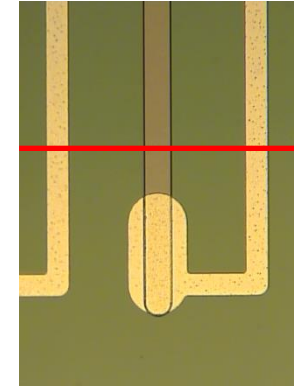
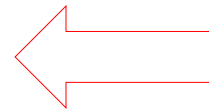
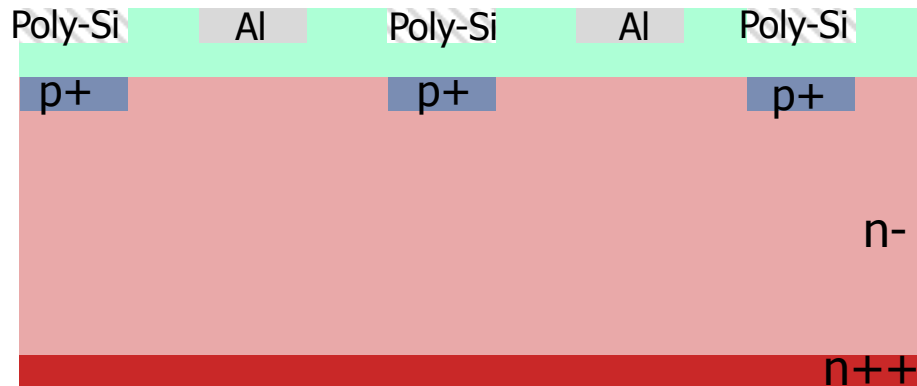
- Induced signal on metallic vias superposed to “direct signal” propagated through polysilicon electrode.

Impact points. Strip Center



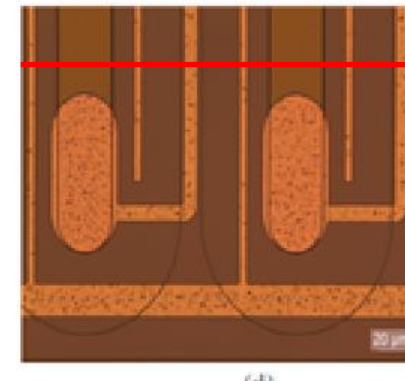
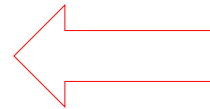
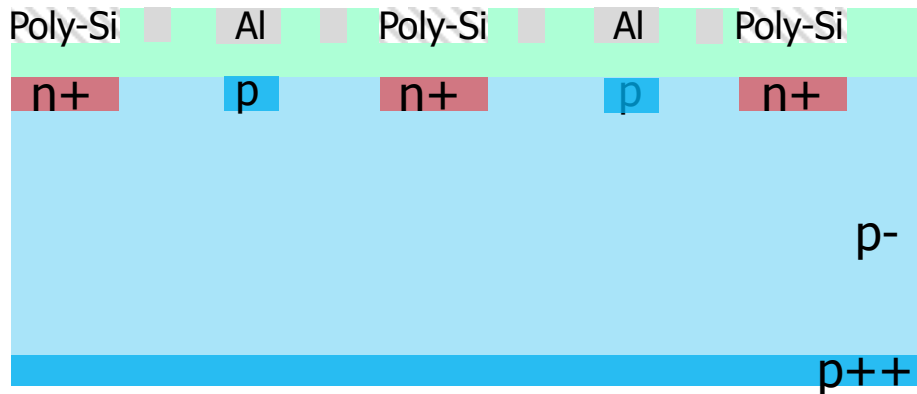
Measured Fractional position shows a clear bias

Isolation structures for cross-talk suppression



Al Poly-Si Al

OLD
DESIGN

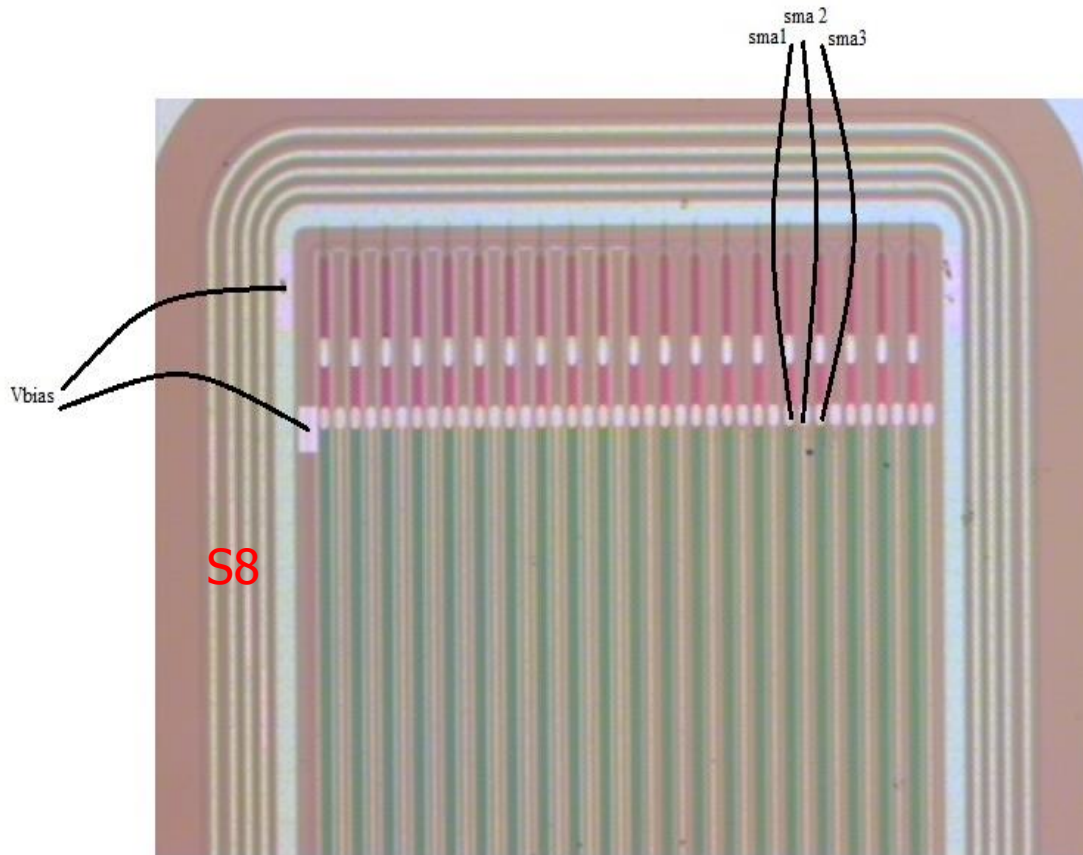


NEW
DESIGN
Common
P-stop
and field
plates

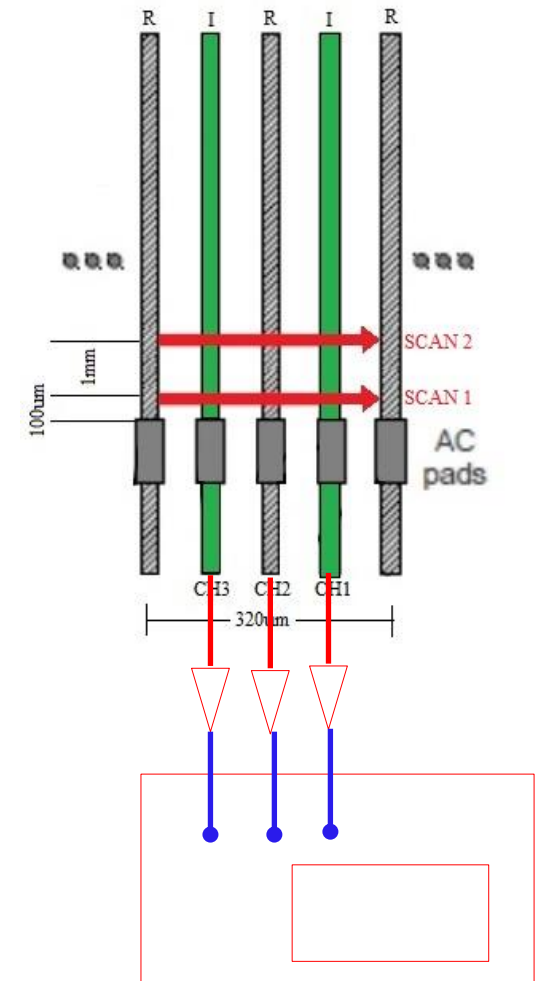
Spin-off of FOSTER sensors proposed by KIT at CMS

Crosstalk suppression (common stop)

- Time Resolved Readout IR-laser induced (e-TCT like measurement)



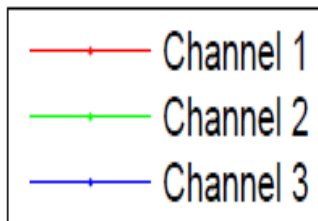
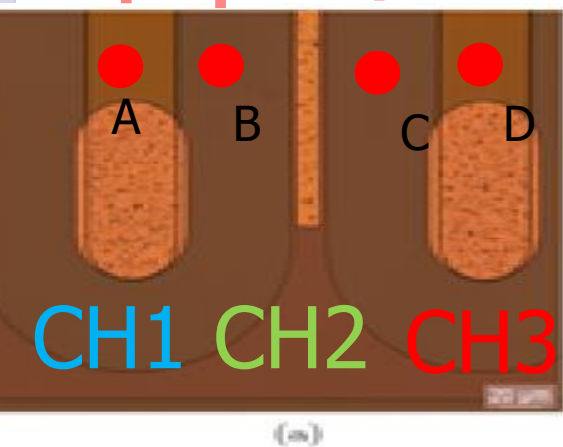
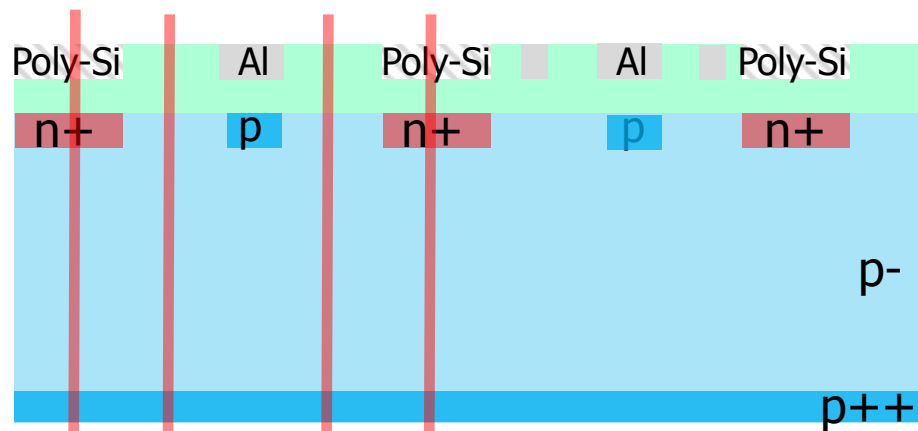
No grid Al. Implant – Al routing – Implant



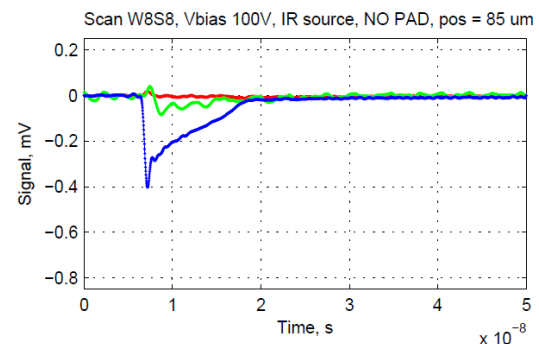
Crosstalk Suppression: Current pulses

Infrared pico second laser

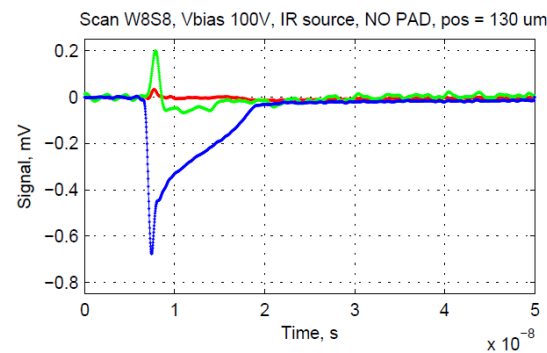
(fast, 1GHz readout channel)



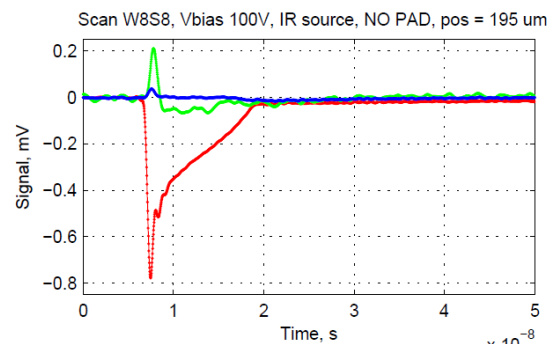
A



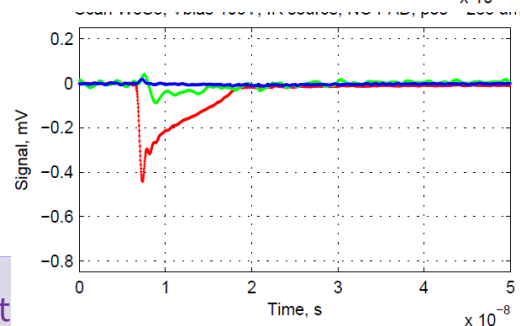
B



C

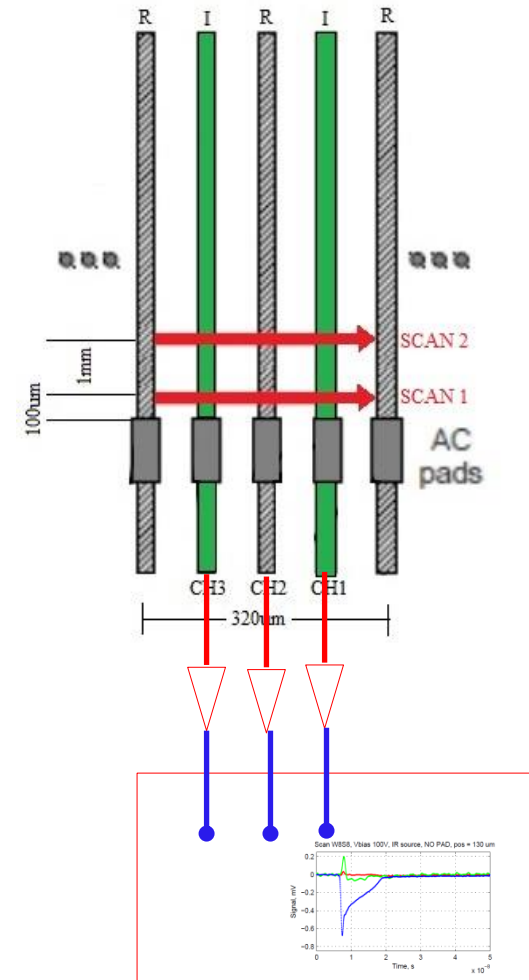
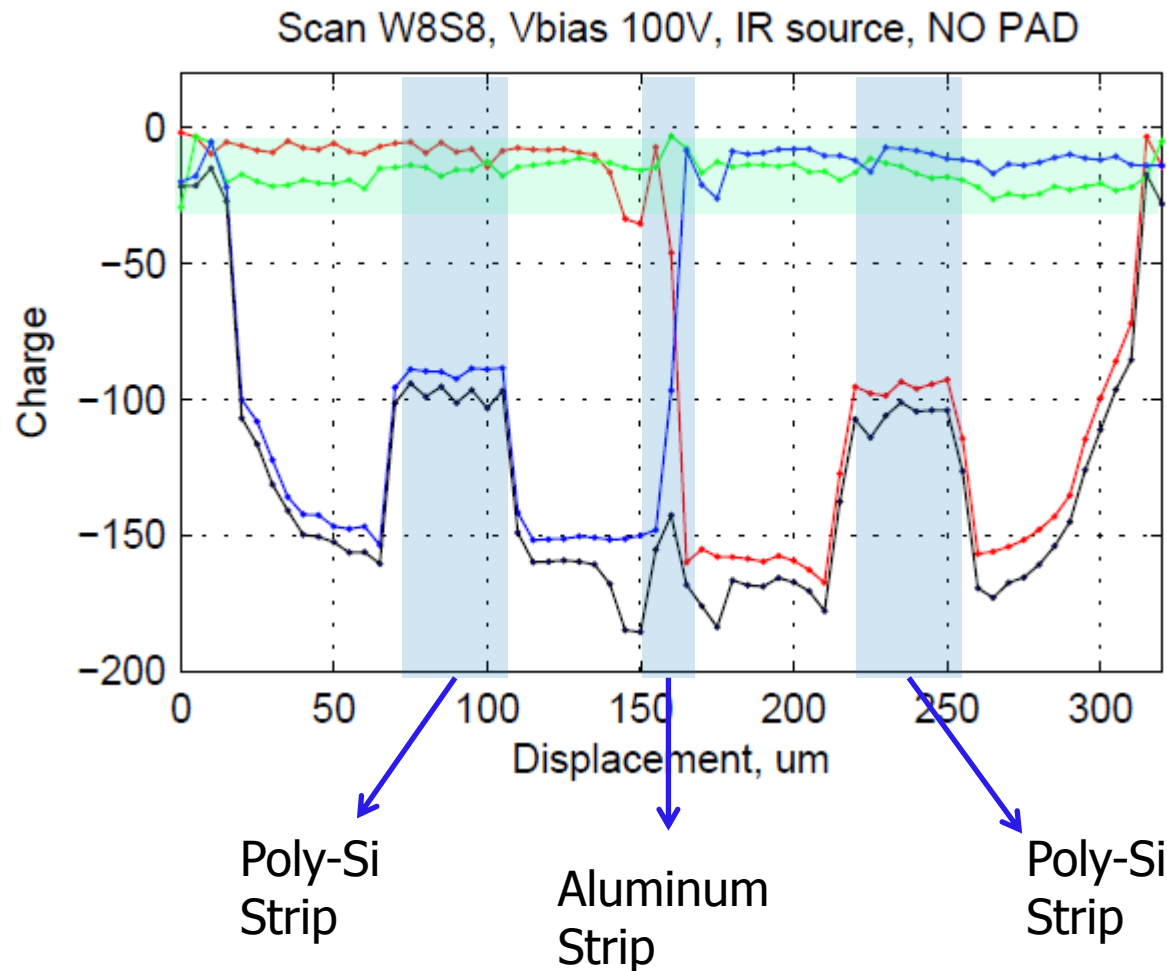


D

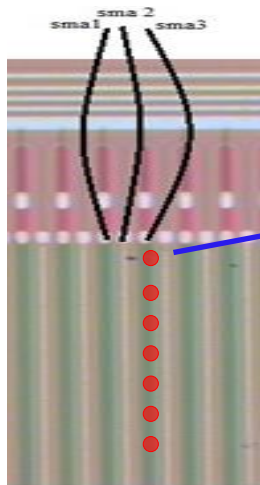


Cross-talk suppression: Integrated charge

Flat charge pedestal for Al routing track, suppressed by calibration



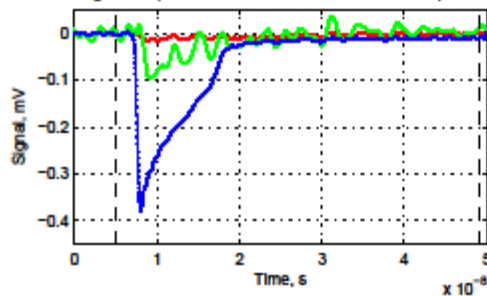
Signal Attenuation studies



Laser longitudinal scan
(42 points, 500um steps)

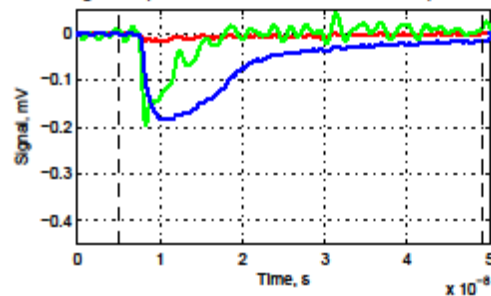
Time-resolved study of the pulse shape and charge

Scan W8S8, Longitudinal por CH3, Vbias 100V, IR Tune = 80, Step 500um



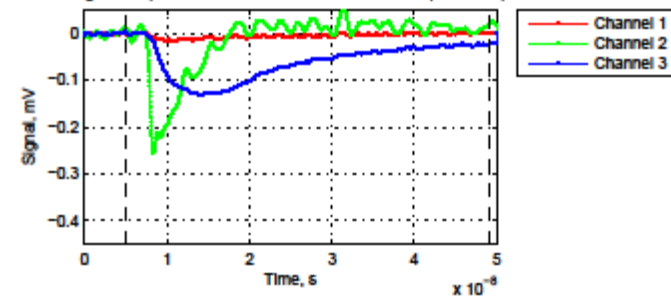
0 mm from r/o pad

can W8S8, Longitudinal por CH3, Vbias 100V, IR Tune = 80, Step 500um, p



5 mm from r/o pad

san W8S8, Longitudinal por CH3, Vbias 100V, IR Tune = 80, Step 500um, pos = 10000 um

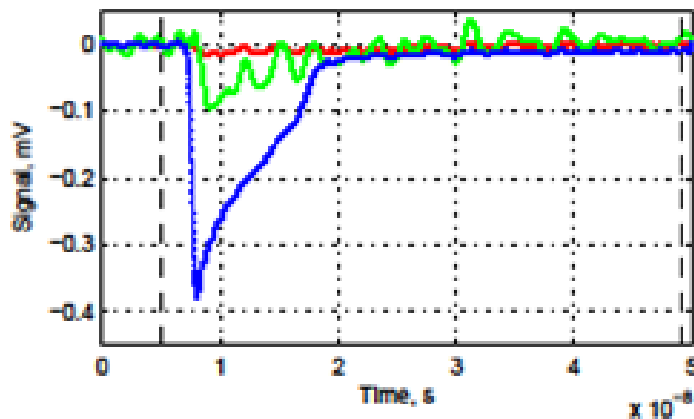


10 mm from r/o pad

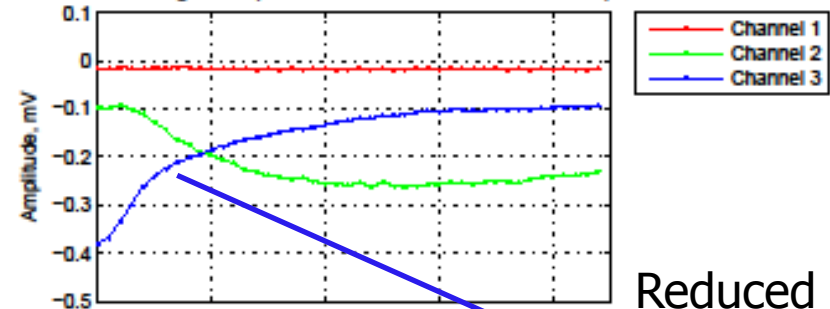
Signal Attenuation studies (2)

Charge and amplitude vs. distance

Scan W8S8, Longitudinal por CH3, Vbias 100V, IR Tune = 80, Step 500um,

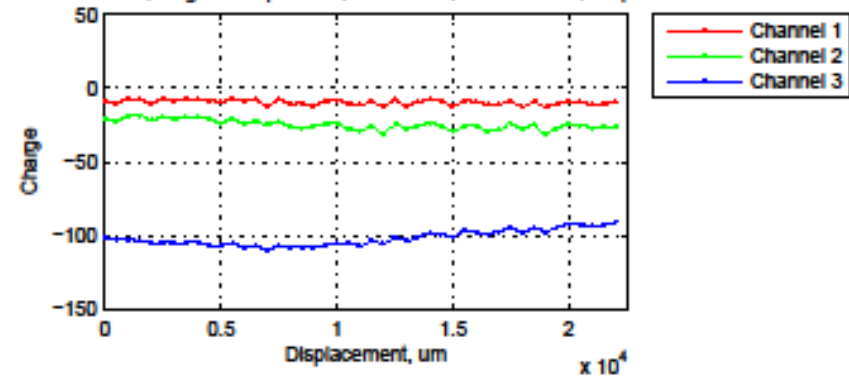


Scan W8S8, Longitudinal por CH3, Vbias 100V, IR Tune = 80, Step 500um



Reduced Amplitude

Scan W8S8, Longitudinal por CH3, Vbias 100V, IR Tune = 80, Step 500um



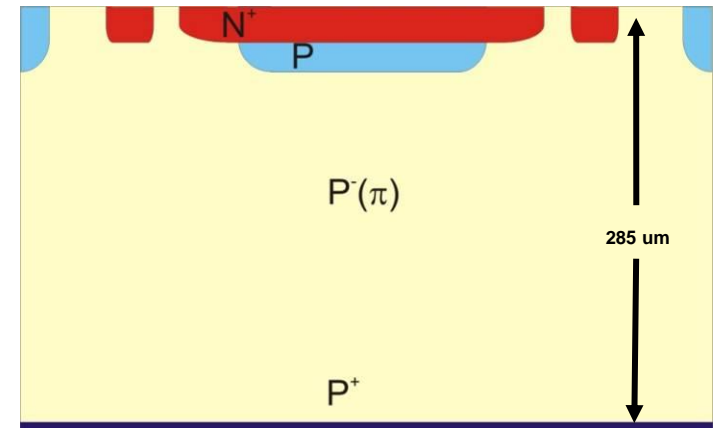
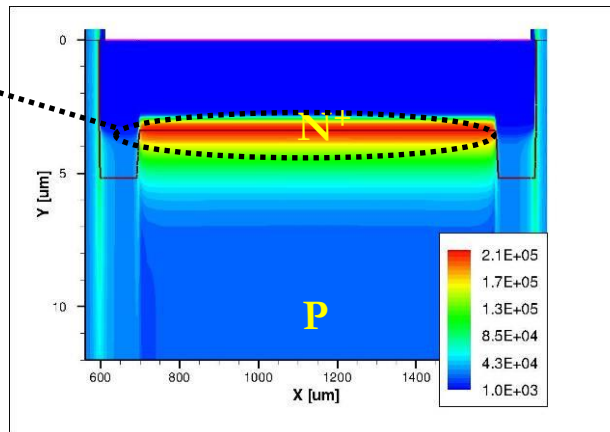
Constant charge

Increasing the signal: LGAD

Implanting an $n^{++}/p^{+}/p^{-}$ junction along the centre of the electrodes. Under reverse bias conditions, a high electric field region is created at this localised region, which can lead to a multiplication mechanism (impact ionization).

Advantages = Thinning while keeping same S/N as standard detectors.

High Electric Field region leading to multiplication



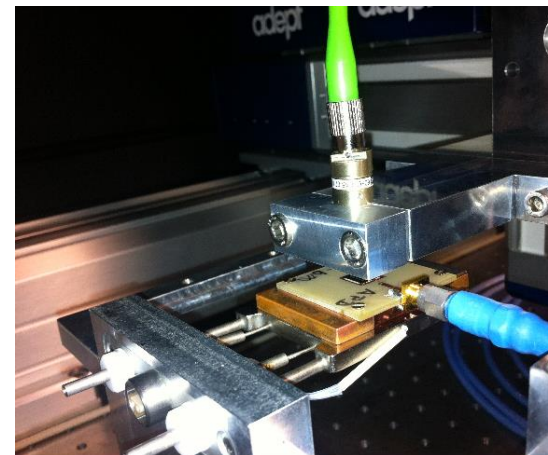
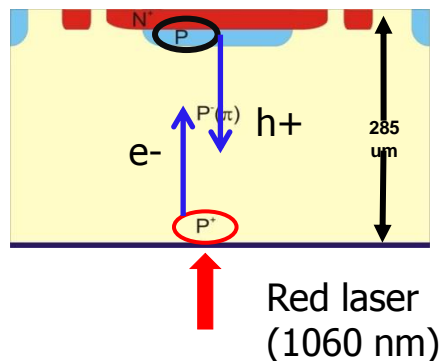
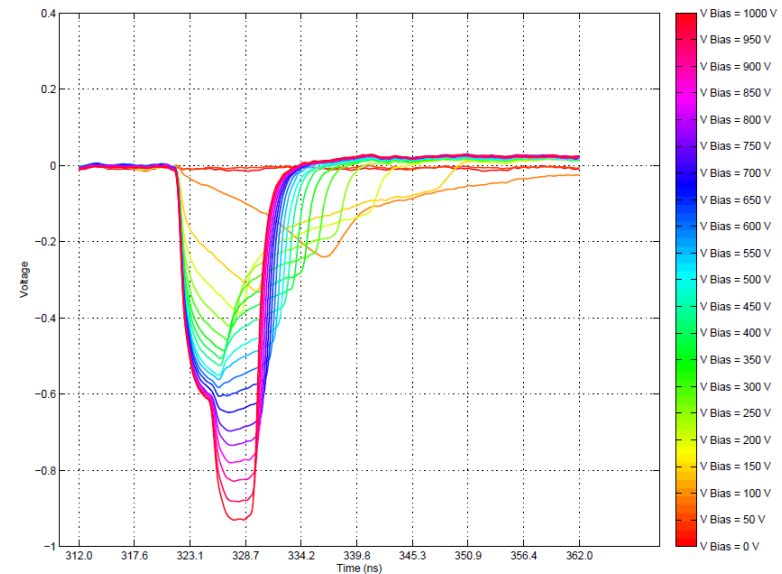
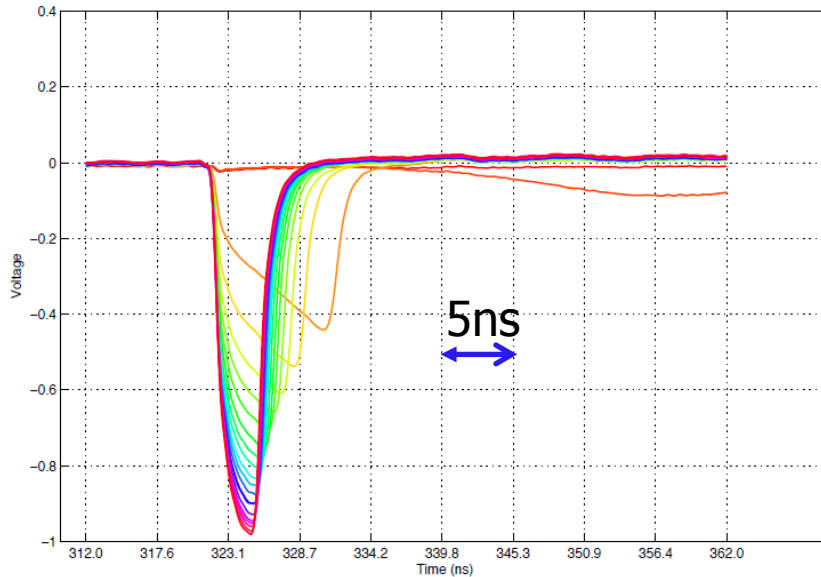
P. Fernandez et al, "Simulation of new p-type strip detectors with trench to enhance the charge multiplication effect in the n-type electrodes", Nuclear Instruments and Methods in Physics Research A 658(2011) 98–102.

PAD LGAD: Red laser TCT characterization

Bottom injection

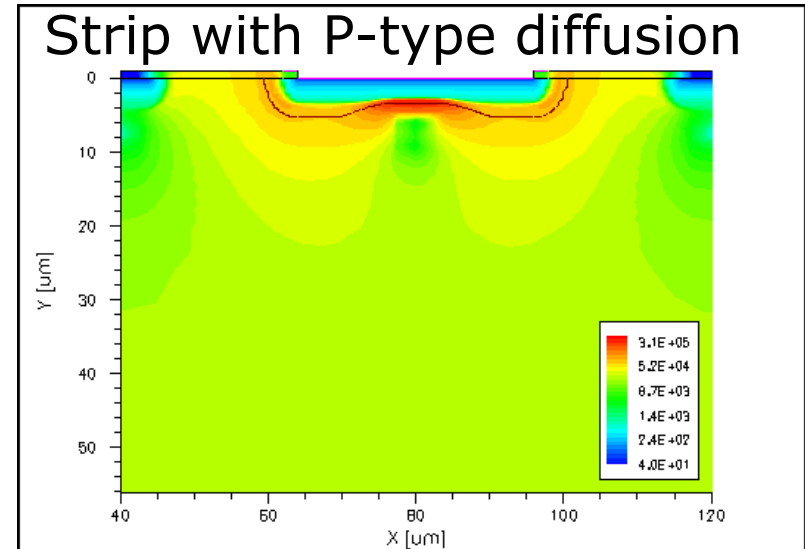
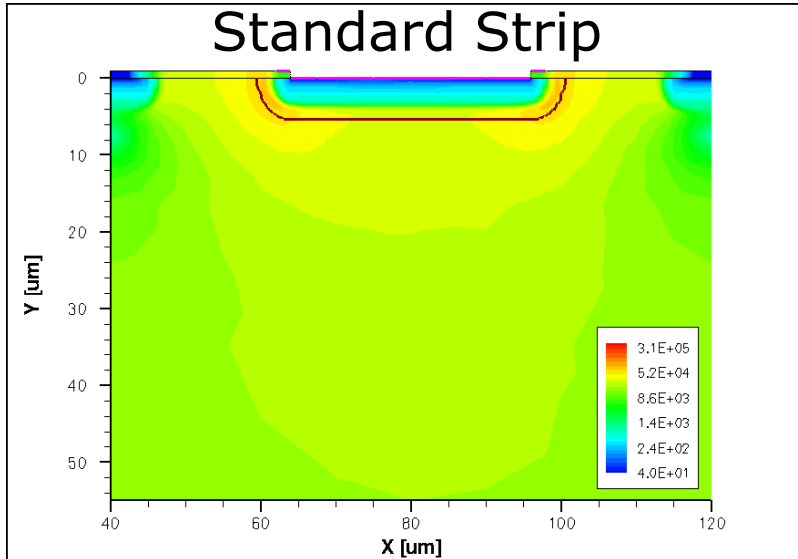
Standard diode n on p

P-type diffusion diode

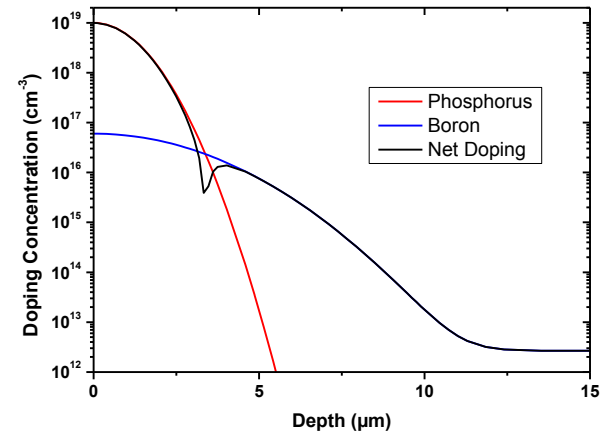
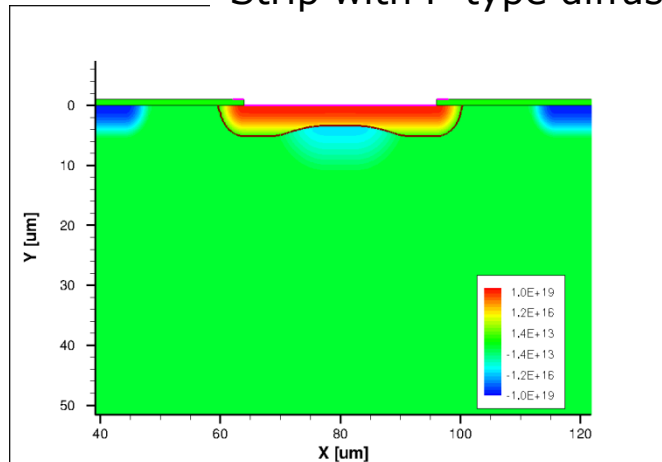


Strip LGAD: Electric Field

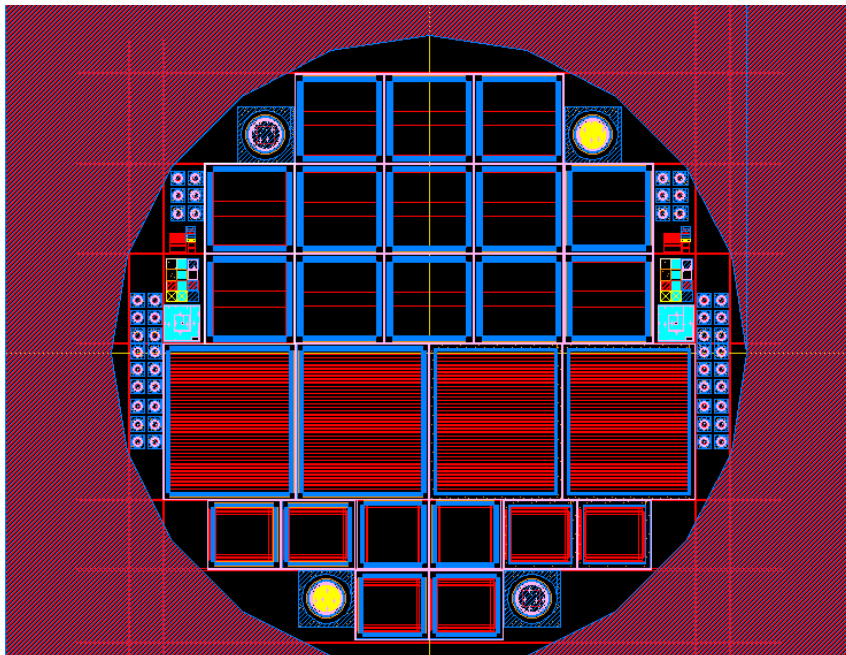
- To obtain the manufacture parameters (doping profiles)



Strip with P-type diffusion: 2D and 1D doping profiles



Current status: preliminary results on strips



RD50 LGAD GROUP

(CERN, CNM, Barcelona, Torino, Ljbljiana, Santander, SCIPP, Freiburg, Glasgow, Liverpool)

- Very preliminary test do not show signal amplification.
- New run in progress and new concept to implement: p-on-p sensor (holes readout with electron amplification in a non-structured anode (pad-like) to ensure uniform amplification

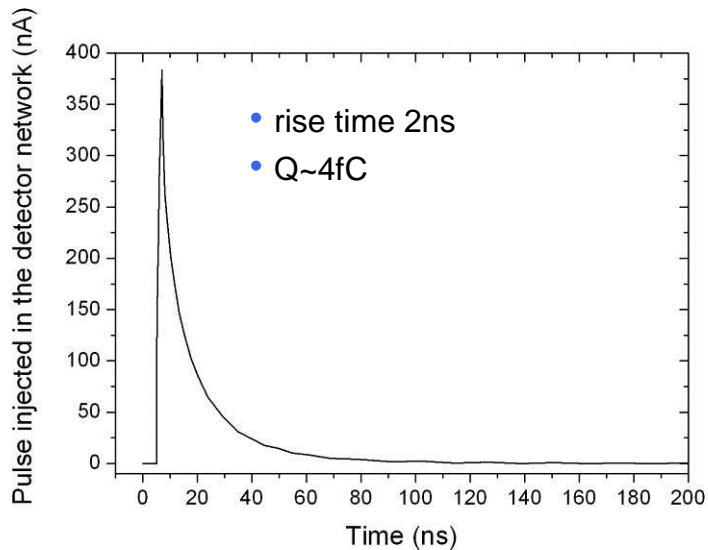
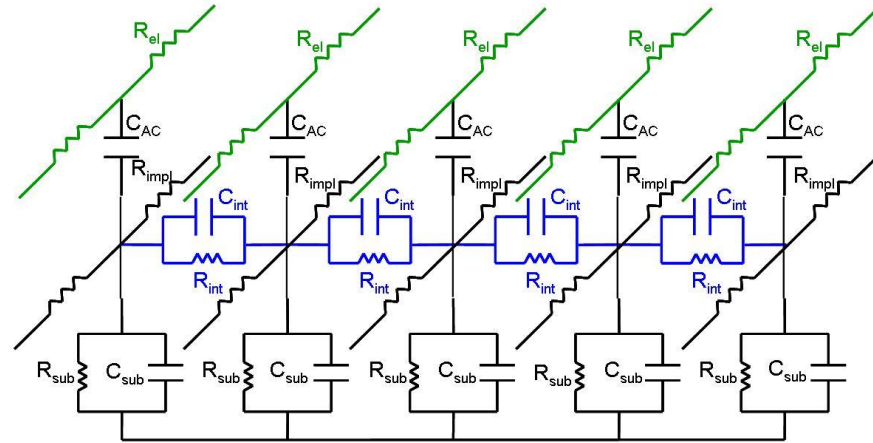
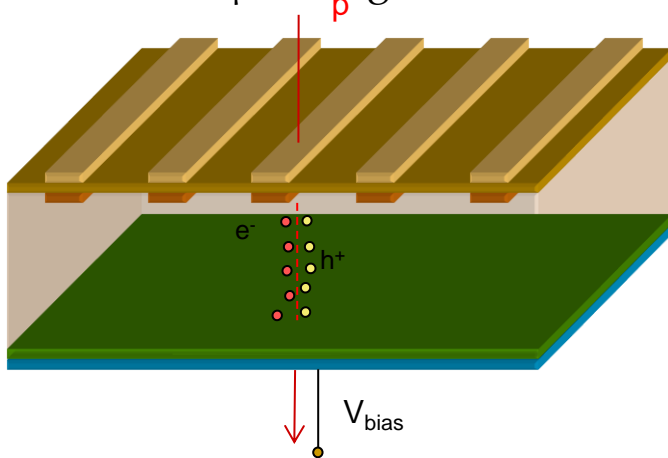
Summary

- A novel 2D position-sensitive semiconductor detector concept based on the resistive charge-division readout method and manufactured using standard semiconductor planar techniques has been introduced.
- A full testing cycle of this technology has been successfully completed: laser, RS and test beam source.
- To be used as a tracking sensor suitable:
 - Single end readout → the integration in the sensor of signal routing tracks
 - Increase SNR → Reduction of the strip resistivity and Linear gain of the signal
- The first issue has been tackled integrating isolation structures (preliminary results are positive).
- New detector designs aim to fabricate detectors with moderate gain (RD50) and p-on-p strip LGAD.

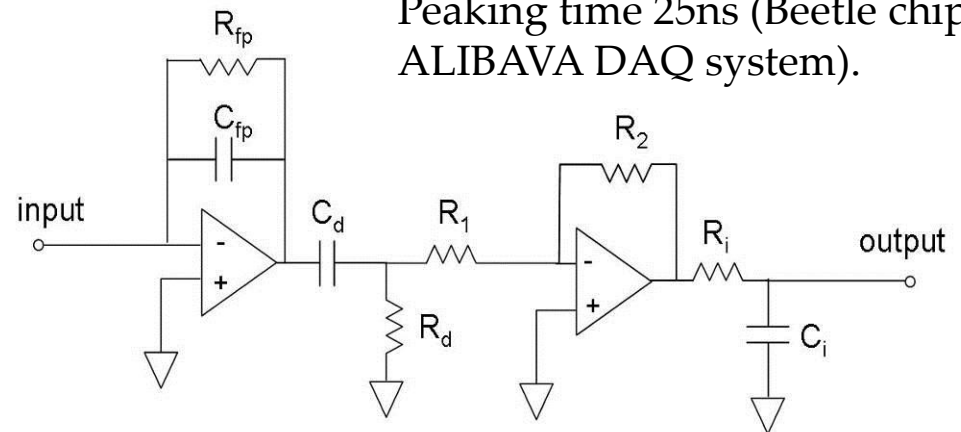
THANK YOU !

Equivalent Electrical Circuit

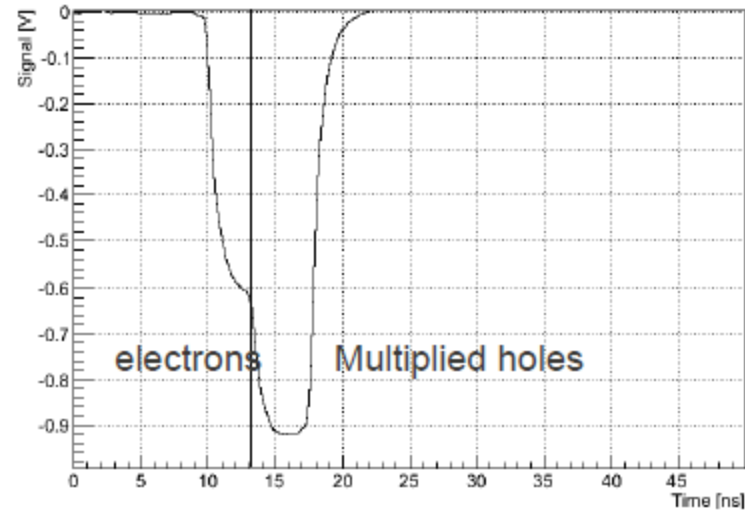
Detector (p^+ -on-n) model ***
80 cells 250 μm long



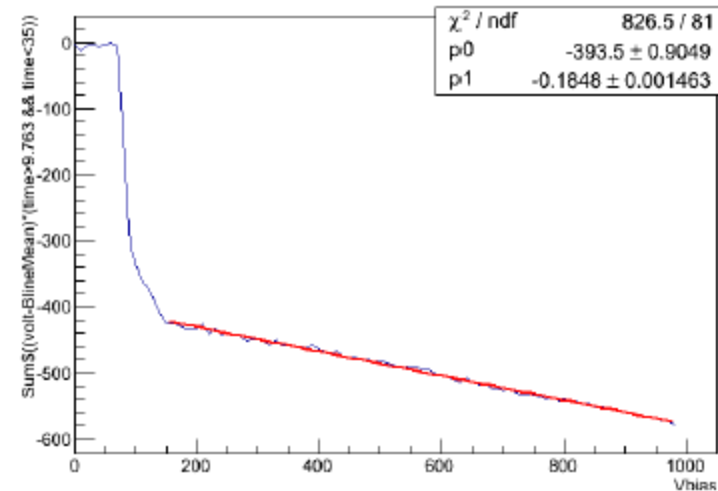
Peaking time 25ns (Beetle chip
ALIBAVA DAQ system).



At $V \gg V_{dep}$ (for instance 980V) the RC tails are short. Check it with simulation:



$$\text{Gain}(V=980) = Q(\text{holes}) / Q(\text{electrons}) = 3$$

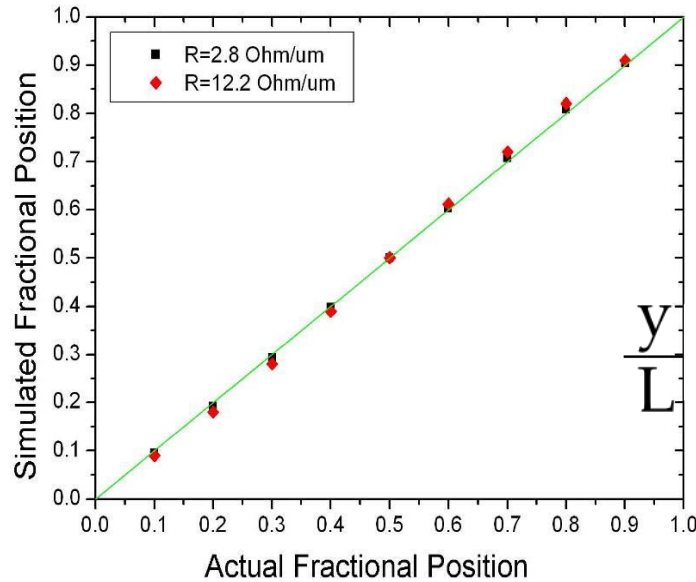


Gain at lower voltages, extracted from CCE curve:

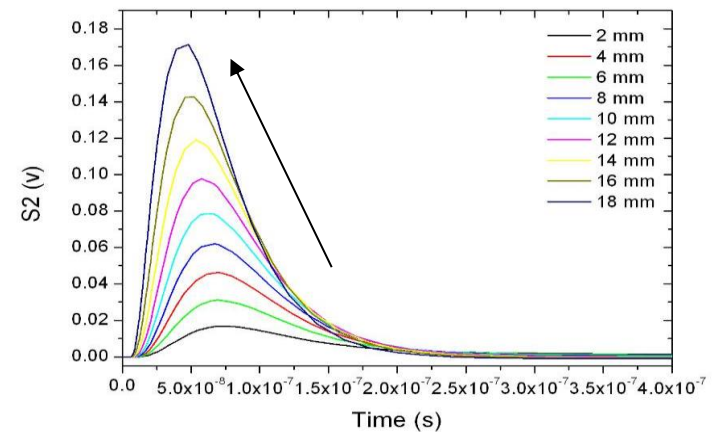
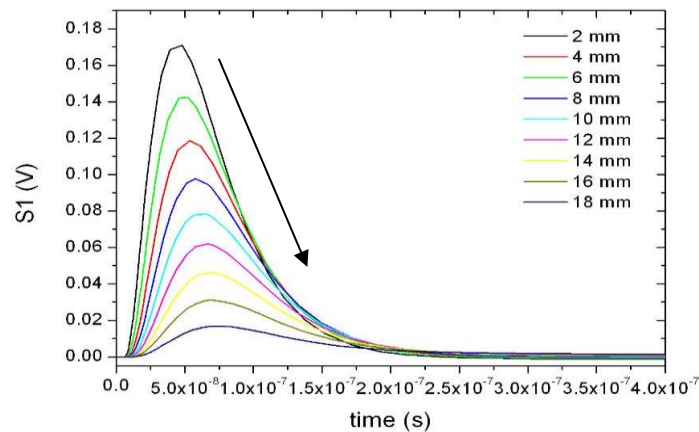
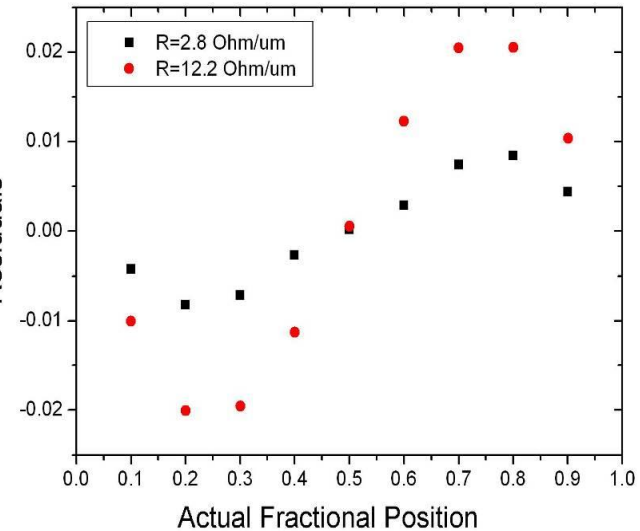
$$\text{CCE}(980) / \text{CCE}(140) = \text{Gain}(980) / \text{Gain}(140)$$

Then $\text{Gain}(140) = 2.2$

Signal Propagation – Linearity (Simulation)



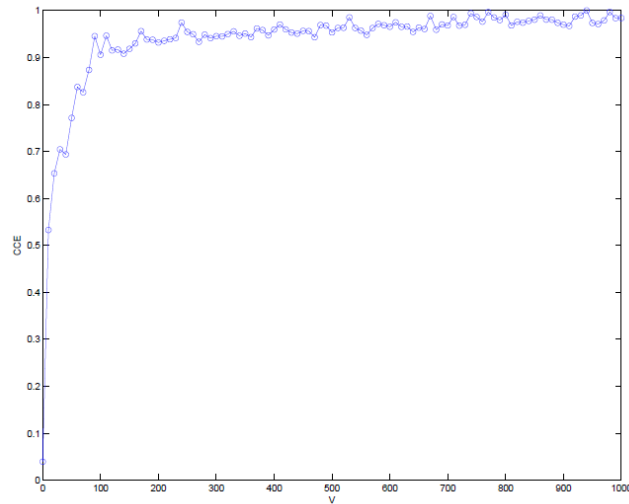
$$\frac{y}{L} = \frac{A_2}{A_1 + A_2} \text{Residuals}$$



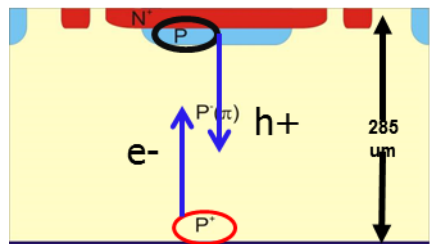
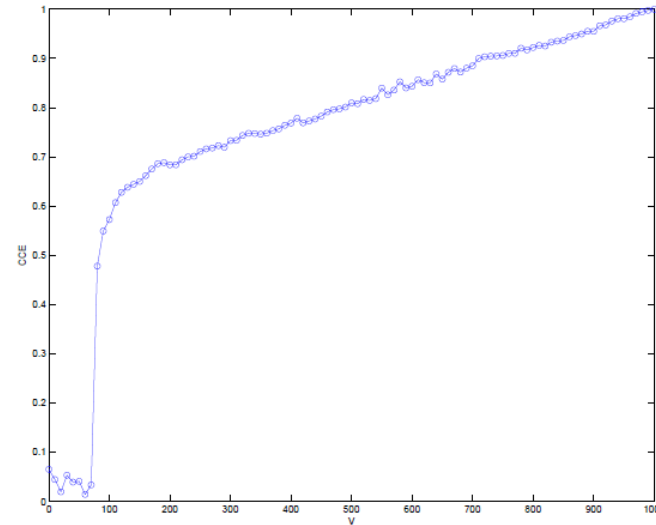
Red laser TCT characterization

Charge collection efficiency

Standard diode



P-type diffusion diode



Red laser
(1060 nm)

